



Half-Size Crystal Can Welded • DPDT **Dry Circuit to 2 Amps**

SPECIFICATIONS

GENERAL

Contact Arrangement	2PDT (2 Form C)
Weight	0.25 oz approx.
Designed to meet the require	ements of MIL-PRF-39016.

PERFORMANCE

Contact Rating (Note 1):

2 Amps @ 28 VDC or 115V 400 Hz
(Case Ungrounded)
10-50 μA @ 10-50 mv DC
or peak AC (Note 4)
100,000 operations minimum
@ rated load, 125°C
250 mw approx.
ime4 ms max, excluding bounce time at nominal coil voltage

Contact Bounce Time	2 ms max @ 2 Amps
	28 VDC

Co

0.050 Ohms max @ 2 Amps
and 6 VDC
0.100 Ohms max @ 2 Amps
and 6 VDC

ENVIRONMENTAL

Temperature Range	65°C to +125°C
Vibration (Note 2)	
	20 G's 38 - 2,000 Hz
Shock (Operating)(Note 2)	50 G's 11 ms

ELECTRICAL CHARACTERISTICS

Duty Cycle	 	C	ontinuous
Insulation Resistance			
	 _	_	0 -

10,000 megohms @ 500V 25°C 1,000 megohms @ 500V 125°C

Dielectric Strength:

Sea Level:

Contact to Case	1,000 VRMS
Contact to Coil	1,000 VRMS
Coil to Case	500 VRMS
Across Open Contacts	500 VRMS
70,000 Feet:	
All Points	350 VRMS

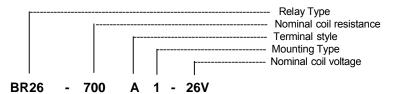
Notes

- 1. For case grounded loads and other ratings, consult the factory.
- 2. For applications requiring other shock and vibration levels, consult the factory.
- 3. For other ratings consult the factory.
- 4. Relay contacts which have switched high level currents are no longer suitable for switching low level loads.



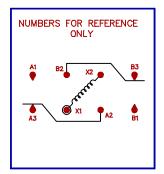
COIL DATA

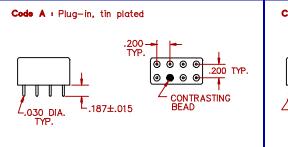
MODEL BR26 PART NUMBER	BR26-37()()-6V	BR26-150()()-12V	BR26-700()()-26V
NOMINAL COIL VOLTAGE	6 VDC	12 VDC	26 VDC
MAXIMUM COIL VOLTAGE	7.3 VDC	14.8 VDC	32 VDC
PULL IN VOLTAGE (MAX @ +125°C)	4.4 VDC	8.4 VDC	18 VDC
PULL IN VOLTAGE (MAX)	3 VDC	6 VDC	13 VDC
DROP OUT VOLTAGE (MIN)	0.3 VDC	0.6 VDC	1.3 VDC
COIL RESISTANCE ± 10% @ 25°C	37 OHMS	150 OHMS	700 OHMS

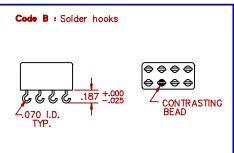


SCHEMATIC TERMINAL VIEW

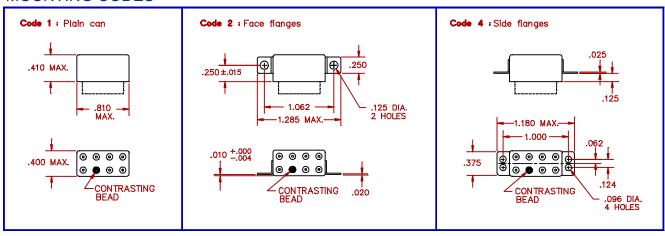
TERMINAL STYLES







MOUNTING CODES



GENERAL NOTES

- Unless otherwise specified, all tests made at nominal coil voltages, @ 25°C.
- For special coil variations, switching configurations, terminals styles and mounting types, consult the factory.
- Unless otherwise specified, tolerances on decimal dimensions are ± .010".
- Specifications contained herein are subject to change without notice.



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